

Title (en)  
SEMICONDUCTOR WAFER ARRAY

Publication  
**EP 0314437 B1 19920715 (EN)**

Application  
**EP 88310029 A 19881025**

Priority  
US 11463387 A 19871028

Abstract (en)  
[origin: EP0314437A1] A semiconductor wafer array comprising a plurality of wafers (10-18) of semiconductor material. Each of the wafers (10-18) is provided with cone-shaped or pyramid-shaped vias (25). Inserted in each of the vias (25) is a correspondingly shaped wad of electrically conductive compliant material for foaming continuous vertical electrical connections between the wafers (10-18) in the stack. The base of each wad makes connection to a bonding pad (32-37) on the surface (30) of a lower wafer (10-18) as well as to the electrically conductive compliant material in the lower wafer (10-18).

IPC 1-7  
**H01L 25/065**

IPC 8 full level  
**H01L 21/768** (2006.01); **H01L 23/48** (2006.01); **H01L 23/52** (2006.01); **H01L 23/538** (2006.01); **H01L 25/065** (2006.01); **H01L 27/00** (2006.01)

CPC (source: EP US)  
**H01L 21/76898** (2013.01 - EP US); **H01L 23/48** (2013.01 - EP US); **H01L 23/481** (2013.01 - EP US); **H01L 23/5384** (2013.01 - EP US); **H01L 25/0657** (2013.01 - EP US); **H01L 25/50** (2013.01 - EP US); **H01L 2224/16145** (2013.01 - EP US); **H01L 2224/16237** (2013.01 - EP US); **H01L 2225/06513** (2013.01 - EP US); **H01L 2225/06517** (2013.01 - EP US); **H01L 2225/06527** (2013.01 - EP US); **H01L 2225/06541** (2013.01 - EP US); **H01L 2225/06582** (2013.01 - EP US); **H01L 2225/06589** (2013.01 - EP US); **H01L 2924/01019** (2013.01 - EP US)

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